



## Material Content Data Sheet



<b>Sales Product Name</b>		BSV236SP H6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000952076						
<b>Package</b>		PG-SOT363-6-6		<b>Weight*</b>		6.65 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.004	0.06		606	
	noble metal	gold	7440-57-5	0.016	0.24		2352	
	inorganic material	silicon	7440-21-3	0.177	2.67	2.97	26654	29612
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		99	
	non noble metal	titanium	7440-32-6	0.003	0.05		495	
	non noble metal	chromium	7440-47-3	0.010	0.15		1484	
	non noble metal	copper	7440-50-8	3.275	49.25	49.46	492691	494769
wire	non noble metal	copper	7440-50-8	0.011	0.17	0.17	1657	1657
encapsulation	organic material	carbon black	1333-86-4	0.029	0.43		4304	
	plastics	epoxy resin	-	0.615	9.25		92534	
	inorganic material	silicondioxide	60676-86-0	2.217	33.36	43.04	333551	430389
leadfinish	non noble metal	tin	7440-31-5	0.213	3.21	3.21	32073	32073
plating	noble metal	silver	7440-22-4	0.076	1.15	1.15	11500	11500
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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